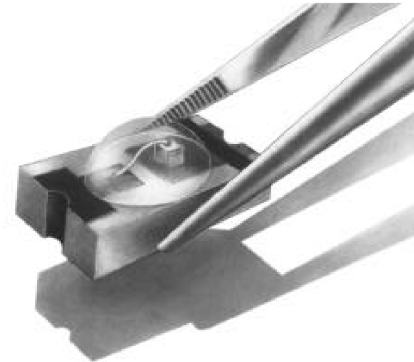


CR 10 PG

Features

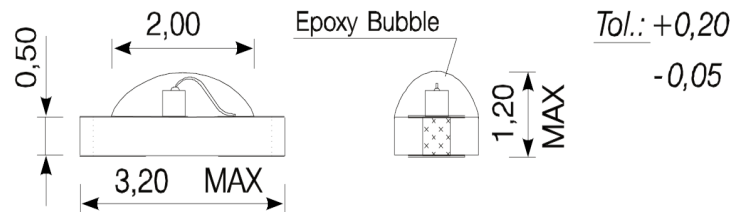
- Solid State Ceramic Chip
- Surface Mounting Device
- High Power Thermal Absorption
- Superior Light Uniformity Over 180°
- End to End Side to Side Stackable Down to a Pitch of 1,33mm
- Solder Pads Conform to Mil-Std 883B
- Strong Contrast w/Other Colors
- Green Clear Lens



Applications

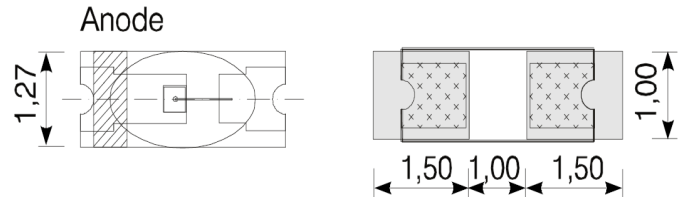
- Ideal For Back Light Applications
- Custom Configurations

ALL MEASUREMENTS IN mm



Maximum Ratings (Ta=25°C)

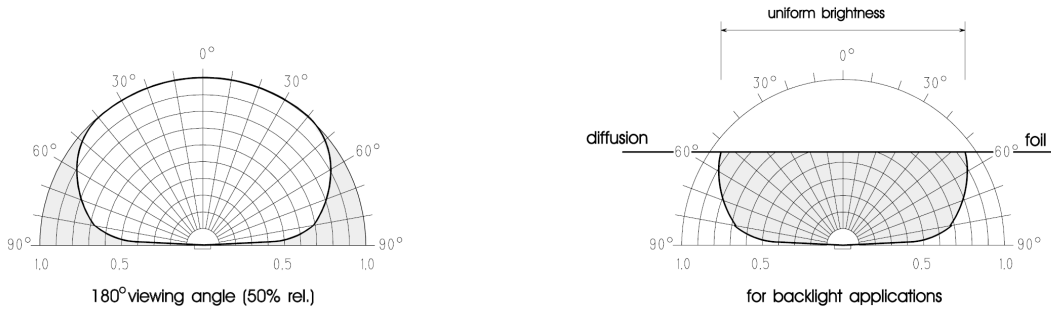
Characteristic	Symbol	Max.	Unit
Forward Current	I _F	75	mA
Reverse Voltage	V _R	20	V
Power Dissipation	P _D	130.00	mW
Operating Temperature	T _{opr}	-25 ~ +80	°C
Storage Temperature	T _{stg}	-25 ~ +120	°C
Soldering Temperature	T _{sol}	250	°C
Soldering Time	-	for 10 sec. max	-



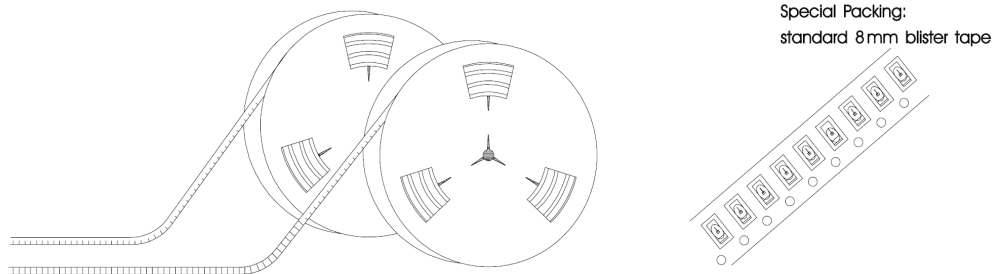
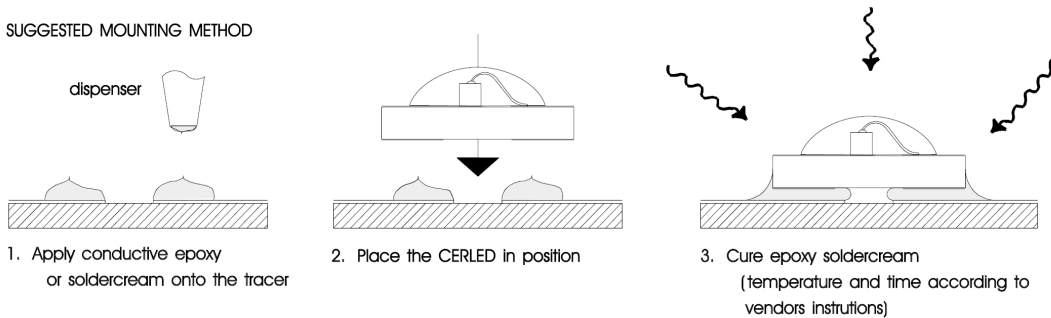
Opto-Electrical Characteristics (Ta=25°C)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage	V _F	I _F =20mA	-	2.30	2.50	V
Reverse Current	I _R	V _R =5V	-	-	100	µA
Luminous Intensity	I _v	I _F =20mA	.80	1.20	-	mcd
Viewing Angle	2θ ^{1/2}	-	-	180°	-	deg.
Peak Wavelength	λ _p	I _F =20mA	-	567	-	nm
Dominant Wavelength	λ _d	I _F =20mA	-	573	-	nm
Spectral Line Half Width	Δλ	I _F =20mA	-	30	-	nm

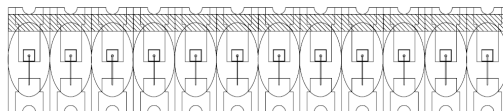
CR 10 PG Graphs



SUGGESTED MOUNTING METHOD



ARRAYS



code to order strips:
CR10 XX -__10
No of LEDs

Available in strips up to 12 CERLEDs with a max. pitch tolerance in spacing and linearity of $\pm 0,01$ mm between chip centers.